

TG-A1250

Ultra Soft Thermal Pad

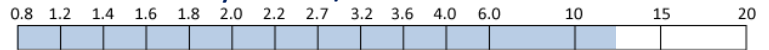
REACH RoHS UL



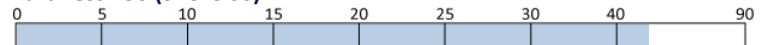
Features

- High thermal conductivity
- Low thermal resistance
- High compressibility and compliancy
- Electrical insulation

Thermal Conductivity : 12.5 W / mK



Hardness : 50 (Shore 00)

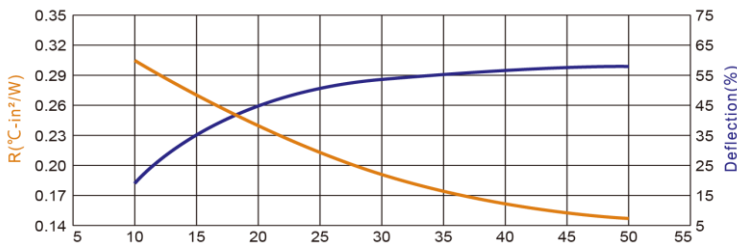


Applications

Best for high power applications

Electronic components: IC, CPU, MOS, LED, Mother Board, Power Supply, Heat Sink, LCD-TV, Notebook, PC, Telecom Device, Wireless Hub, DDR II Module, DVD Applications, Hand-set applications etc.

Thermal Resistance VS. Pressure VS. Deflection



Pressure (psi)	R (°C-in ² /W)	Deflection (%)
10	0.304	19
30	0.194	53
50	0.147	58

Properties

Properties	TG-A1250	Unit	Tolerance	Test Method
Thermal Conductivity	12.5	W / mK	±10%	ASTM D5470
Thickness	0.5~8.0	mm	-	ASTM D374
	0.0197~0.315	inch	-	ASTM D374
Color	green	-	-	Visual
Flame Rating	V-0	-	-	UL 94
Dielectric Breakdown Voltage	6.5	KV / mm	±10%	ASTM D149
Weight Loss	<1	%	-	ASTM E595
Density	3.3	g / cm ³	±10%	ASTM D792
Working Temperature	-50 ~ +150	°C	-	-
Volume Resistance	1 x 10 ¹³	Ohm-m	-	ASTM D257
Elongation	40	%	-	ASTM D412
Standard Shape	Sheet ones	-	-	-
Hardness	50	Shore 00	±8	ASTM D2240

Need samples? Pre-cut for different shapes

T-Global Techonology Co., Ltd

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